

## ABSTRACT OF THE DISCLOSURE

A device and method for improving the uniformity of resist layers. The method includes controlling the evaporation of solvent from a deposited resist layer by impinging a control fluid onto a deposited resist layer. Optional sensing of flow parameters and other environmental conditions (such as temperature or humidity) adjacent the deposited resist layer, as well as determining whether a deviation exists between the sensed parameter(s) and a predetermined reference amount, and adjusting the appropriate parameter(s) to reduce the deviation if such deviation exists could also be performed. The device may also include a rotatable substrate support that can be used in conjunction with the control fluid supply.